To the Honorable Commissioner of Pate

REC

05-31-2000



SHEET

U.S. Department of Commerce Patent and Trademark Office

riginal documents or copy thereof

1. Name of conve	eying party(i、	101369	889	dress of receiving party(ies):
Brian A. Vaartstra 5-17.0		• • •	Name: Micron	Technology, Inc.
V	5.17.6	9 0	Internal Address	6.6
Additional name(s) of conveying Yes party(ies) attached? X No			Street Address: 8000 S. Federal Way	
3. Nature of Conveyance:			Boise, Idaho 83706-9632	
x Assignment Merger			City: Boise	
Security Agreement Change of Name			State: Idaho	Zip: 83706-9632
Other			Country: U.S.	
Execution Date(s): 5/11/00			Additional name(s) & Yes address(es) attached? x No	
Application number(s) or patent number(s):				
If this document is being filed together with a new application, the Execution date(s) of the new application is (are): 5/11/00				
A. Patent Application No.(s): B. Patent No.(s):				
791572079			Additional numb	ers attached? Yes X No
5. Name and address of party to whom correspondence concerning document should be mailed:			6. Total number of applications and 1 patents involved:	
Name: DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP			7. Total fee (37 0	C.F.R 3.41) \$\$40.00
Internal Address:	Atty. Dkt.: M4065.024	12/P242	x Enclosed	
Attr	n:Thomas J. D'Amico		Authorize	ed to be charged to deposit account
Street Address:	2101 L Street NW			y overpayment or underpayment
City: Washington	State: Zip: 2003	37 - 1526	8. Deposit acco	unt number: 4 - 1073
DO NOT USE THIS SPACE				
9. Statement and signature.				
To the hest of my knowledge and belief, the foregoing information is true and correct and by attached				
copy is a true copy of the original document.				
Thomas J. D MARK T	Hearson	Signature		Date 6
· · · · · · · · · · · · · · · · · · ·		Signature		
Reg. No. 28,371 33,08Z Total number of pages including cover sheet, attachments, and document: 3				
Total number of pages including sover chost, and an army and a second chost, and a sec				

1147719 v1; _LL301!.DOC

REEL: 010812 FRAME: 0524

Docket No.: M4065.0242/P242 Micron No.: 98-1058

ASSIGNMENT AND AGREEMENT

For value received, I, Brian A. Vaartstra hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled FLOW-FILL STRUCTURES, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

1106225 v1; NPKH01!.DOC

PATENT REEL: 010812 FRAME: 0525

Docket No.: M4065.0242/P242

Micron No.: 98-1058

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Brian A. Vaartstra

Date:

United States of America

State of IDAHO)ss.

County of ADA)

On this 11 day of way, , 2000, before me personally came Brian A. Vaartstra, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

MOTARY

AUBLIC

OF IDARIGHMENT

1106225 v1; NPKH01!.DOC

RECORDED: 05/17/2000

PATENT REEL: 010812 FRAME: 0526